Advanced Lead Frame Services—
From Design to Delivery
CORPORATE OVERVIEW

At QPL Limited, we are committed to delivering total customer satisfaction through product quality and service reliability. From lead frame design to delivery, QPL provides volume production while at the same time offering customers the customization they need for specific requirements. These may include reduced cycle times, customized specifications, thermally and electrically enhanced designs, special quantity orders and an inventory management service. Our flexible approach gives our customers the most reliable and cost-effective solution for sustaining an uninterrupted supply line.

To ensure total customer satisfaction, we maintain the highest standards of customer service. Through streamlined and flexible production standards and on-call customer service, QPL delivers products with industry-renowned quick turnaround times. In-house design teams also allow us to tailor our services to different customer requirements. In addition to custom designs for both etched and stamped lead frames, QPL provides a comprehensive range of standard products including SOIC (Small Outline Integrated Circuit), QFP (Quad Flat Package), TGFP (Thin Quad Flat Package), PDIP (Plastic Dual In-Line Package), PLCC (Plastic Leaded Chip Carrier) and TSOP (Thin Small Outline Package). For customers with a long-term need in lead frame supply, QPL has also developed a partnership program through which both companies work together to determine overall requirements while striving to reduce costs and increase service.

We’re always looking to future development trends in the industry and the needs of our customers. As such, investing in new technology and equipment forms a vital part of QPL’s business strategy. We continuously assess and evaluate how production processes and customer requirements can be refined and improved to increase levels of efficiency and quality. Investments are also being made in new technologies such as laser plotter systems, automatic etching machines, high-speed plating and automatic downset/taping equipment. In addition, we are dedicating resources to licensing technologies (pre-plated lead frames, NiPd (Nickel Palladium), Stiffeners for TBGA (Tape Ball Grid Array) and Heatsinks for Thermal Enhanced Packages, etc.) as well as laser-based inspection systems for everything from mask generation to final testing/inspection operations.

With our high-quality products, experienced personnel and continuous investment and improvement in new technology, QPL is committed to become the most preferred lead frame supplier in the world.
We offer a full range of process capabilities to meet all customer requirements. This makes QPL the partner of choice for one-source lead frame manufacturing, and provides customers with the flexibility they need to customize a design to meet their specific applications.

**Process Flow—Etching**

Photochemical etching is one of the most widely used methods for manufacturing lead frames. A high unit-cost process, it can be tooled with low costs and minimal time requirements. Etched lead frames are manufactured in flat sheets, made of either copper or Alloy 42, on which both sides are coated with photoresist film. Next, surface cleaning is performed, followed by lamination. The photoresist is then exposed to the required lead frame pattern with the aid of an ultraviolet source and a precision pattern glass/film photomask. The areas to be retained as metal are coated with resists and etched parts are kept free of the resist in the finished pattern. Development is achieved by spraying developer onto the image photoresist.

**Process Flow—Stamping**

Stamping is an automated, high-speed process suitable for large production rates that justify the high initial tooling expense. The sheet metal, typically in roll form, is pierced along both edges to create indexing holes that position the sheet during further processing. The location holes are used to advance the sheet metal strip through the stamping machine. Die-and-punch sets specific to the lead frame geometry are also required. The process is typically accomplished as a series of stamping operations that progressively approach the final lead frame geometry—the number of steps dependent on the geometrical complexity of the lead frame.

**Silver Plating**

QPL offers up to 16 lines on one plating machine for faster cycle time, minimizing floor space and additional costs. Lead frames are plated with standard spot/ring/full plating or multi-mini spot plating, with individual lines separately controlled to meet the customer’s quality requirements.

**NiPd Plating**

Through licenses obtained from Texas Instruments and Furukawa, QPL offers substantial advantages by using NiPd-ppf (NiPd pre-plated lead frames). These advantages include the elimination of selective plating, the completion of all wet processes prior to package assembly, and increases in both throughput and production yields. This process also enables significant quality improvements, including enhanced coplanarity maintenance, the elimination of both solder bridging and the possibility of silver migration, and environmental benefits due to the elimination of Cyanide and Lead. Best of all, customers realize overall packaging cost reduction due to simplification of the plating process, the reduction of waste treatment, and the extension of their lead frame shelf-life.
**PLCC** The Plastic Leaded Chip Carrier has leads on all four sides with J-shaped bends and is available with a variety of pad designs, such as dual-pad. Designs with fused leads promote better thermal performance, while those with a closed dambar reduce mold flash and improve the solder plating coverage.

**PDIP/SPDIP** The Plastic Dual In-line Package/Shrink Plastic Dual In-line Package has a rectangular plastic body with two rows of leads that are bent up from the package body at a slight angle. Its most common use is through-hole insertion mounting in applications such as logic, processor and memory devices. QPL also delivers IDF (Interdigitated Frame) versions that enable more lead frames to be oriented along a strip, resulting in increased throughput in assembly.
The Lead On Chip features lead fingers that are attached directly to the surface of the chip using a double-sided adhesive tape. Since there is no die pad on the LOC lead frame, the package allows for higher density, enabling it to accommodate a larger IC chip and providing better reliability performance than traditional packages. These characteristics make LOC packaging a good choice for meeting the increasing capacity and density requirements of DRAM (Dynamic Random Access Memory) designs.

The Tape Ball Grid Array Stiffeners/Heatsinks deliver high performance while reducing the real estate required by QFP and PBGA (Plastic Ball Grid Array) packages. The TBGA Stiffener is the integral top layer of the package and is fabricated from thermally conductive sheet copper. Due to its strength, the stiffener is used for handling the package during assembly, test and reflow on the motherboard. The cavity where the IC chip is placed is etched and can be plated with a gold ring, which provides a wire bondable surface for ground bonds. QPL offers a wide range of TBGA stiffeners for high-performance applications, as well as both etched and stamped heatsinks (heat spreaders).

The Small Outline Integrated Circuit is available in a number of variations, including SOP (Small Outline Package), SSOP (Shrink Small Outline Package), SOJ (Small Outline J-Leaded), TSOP (Thin Small Outline Package), and TSSOP (Thin Shrink Small Outline Package). The SOIC package is desirable for its small footprint on the circuit board. SO lead frames are available in single-pad, dual-pad and matrix designs.

The Quad Flat Pack/Thin Quad Flat Pack is a plastic package with a square or rectangular body with leads on all four sides in a gull-wing configuration. Designs with "dimples" (half-etched holes) on the back side of the pad provide the mechanical adhesion to prevent delamination. Different pad designs exist to further enhance package reliability, while designs with a dual-pad lead frame are available to minimize cost.
QFN The Quad Flat Non-Lead package type delivers the small footprint and low pin count needed for today’s portable devices and high-speed applications demanding high electrical performance in a constrained area. QFNs are miniaturized, low pin-count, perimeter-array packages that use a metallic lead frame for the die assembly and board interconnection. This design allows the use of standard die-attach, wire-bond and encapsulation technologies and equipment. QFN is a lead frame-base CSP (Chip Scale Package) type of package with a “leadless” element that enables superior thermal performance and the ability to view and contact leads after assembly.

QPL has the capability to produce custom designs based on customer request. All parts are available with a standard plating option.
SALES OFFICES:
QPL Ltd. Headquarters
2/F., QPL Industrial Building
138 Texaco Road, Tsuen Wan,
New Territories, Hong Kong
Tel: (852) 24065111
Fax: (852) 24076271

QPL (US) Inc.
45500 Northport Loop West
Fremont, CA 94538
U.S.A.
Tel: (510) 249-1224
Fax: (510) 249-6443

QPL (PTE) Ltd.
150 Cecil Street #09-03
AXA Life Building, Singapore 069543
Tel: (65) 62233878
Fax: (65) 62233032

QPL (Taiwan)
No. 35, Lane 2
Chin Shan 11 Street
Hsin Chu City, 300 Taiwan
ROC
Tel: (886) 3 6867679
Fax: (886) 3 5644371

FACTORIES:
QPL Ltd. Headquarters
2/F., QPL Industrial Building
138 Texaco Road, Tsuen Wan,
New Territories, Hong Kong

Talent Focus Industries Limited
Lain Tang Wei 2nd Road
Lain Tang Wei Industrial Estate, Heao,
Henggang Town, Longgang District,
Shenzhen, China

Dongguan Changan
QPL Electronics Factory
No. 1, QPL Road, Xin An Industrial Park,
Changan Town, Dongguan,
Guangdong, PRC 523860

www.qpl.com